



# PSMN7R0-100XS

N-channel 100V 6.8 mΩ standard level MOSFET in TO220F (SOT186A)

Rev. 3 — 6 March 2012

Product data sheet

## 1. Product profile

### 1.1 General description

Standard level N-channel MOSFET in TO220F (SOT186A) package qualified to 175°C. This product is designed and qualified for use in a wide range of industrial, communications and domestic equipment.

### 1.2 Features and benefits

- High efficiency due to low switching and conduction losses
- Isolated package
- Suitable for standard level gate drive

### 1.3 Applications

- AC-to-DC power supply equipment
- Server power supplies
- Motor control
- Synchronous rectification

### 1.4 Quick reference data

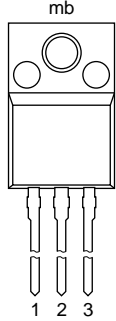
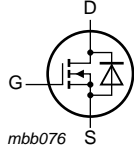
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DS}$	drain-source voltage	$T_j \geq 25\text{ °C}$ ; $T_j \leq 175\text{ °C}$	-	-	100	V
$I_D$	drain current	$T_{mb} = 25\text{ °C}$ ; $V_{GS} = 10\text{ V}$ ; see <a href="#">Figure 1</a>	-	-	55	A
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C}$ ; see <a href="#">Figure 2</a>	-	-	57.7	W
<b>Static characteristics</b>						
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\text{ V}$ ; $I_D = 15\text{ A}$ ; $T_j = 25\text{ °C}$ ; see <a href="#">Figure 12</a> ; see <a href="#">Figure 13</a>	-	5.4	6.8	mΩ
<b>Dynamic characteristics</b>						
$Q_{GD}$	gate-drain charge	$V_{GS} = 10\text{ V}$ ; $I_D = 15\text{ A}$ ; $V_{DS} = 50\text{ V}$ ; see <a href="#">Figure 14</a> ; see <a href="#">Figure 15</a>	-	34	-	nC
$Q_{G(tot)}$	total gate charge		-	121	-	nC
<b>Avalanche ruggedness</b>						
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$V_{GS} = 10\text{ V}$ ; $T_{j(init)} = 25\text{ °C}$ ; $I_D = 55\text{ A}$ ; $V_{sup} \leq 100\text{ V}$ ; unclamped; $R_{GS} = 50\text{ Ω}$ ; see <a href="#">Figure 3</a>	-	-	420	mJ



## 2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		
2	D	drain		
3	S	source		
mb		mounting base; isolated		

SOT186A (TO-220F)

## 3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PSMN7R0-100XS	TO-220F	plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 "full pack"	SOT186A

## 4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DS}$	drain-source voltage	$T_j \geq 25\text{ °C}$ ; $T_j \leq 175\text{ °C}$	-	100	V
$V_{DGR}$	drain-gate voltage	$T_j \geq 25\text{ °C}$ ; $T_j \leq 175\text{ °C}$ ; $R_{GS} = 20\text{ k}\Omega$	-	100	V
$V_{GS}$	gate-source voltage		-20	20	V
$I_D$	drain current	$V_{GS} = 10\text{ V}$ ; $T_{mb} = 25\text{ °C}$ ; see <a href="#">Figure 1</a>	-	55	A
		$V_{GS} = 10\text{ V}$ ; $T_{mb} = 100\text{ °C}$ ; see <a href="#">Figure 1</a>	-	38.9	A
$I_{DM}$	peak drain current	pulsed; $t_p \leq 10\text{ }\mu\text{s}$ ; $T_{mb} = 25\text{ °C}$ ; see <a href="#">Figure 4</a>	-	220	A
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C}$ ; see <a href="#">Figure 2</a>	-	57.7	W
$T_{stg}$	storage temperature		-55	175	°C
$T_j$	junction temperature		-55	175	°C
$T_{sld(M)}$	peak soldering temperature		-	260	°C
<b>Source-drain diode</b>					
$I_S$	source current	$T_{mb} = 25\text{ °C}$	-	48	A
$I_{SM}$	peak source current	pulsed; $t_p \leq 10\text{ }\mu\text{s}$ ; $T_{mb} = 25\text{ °C}$	-	220	A
<b>Avalanche ruggedness</b>					
$E_{DS(AL)S}$	non-repetitive drain-source avalanche energy	$V_{GS} = 10\text{ V}$ ; $T_{j(init)} = 25\text{ °C}$ ; $I_D = 55\text{ A}$ ; $V_{sup} \leq 100\text{ V}$ ; unclamped; $R_{GS} = 50\text{ }\Omega$ ; see <a href="#">Figure 3</a>	-	420	mJ

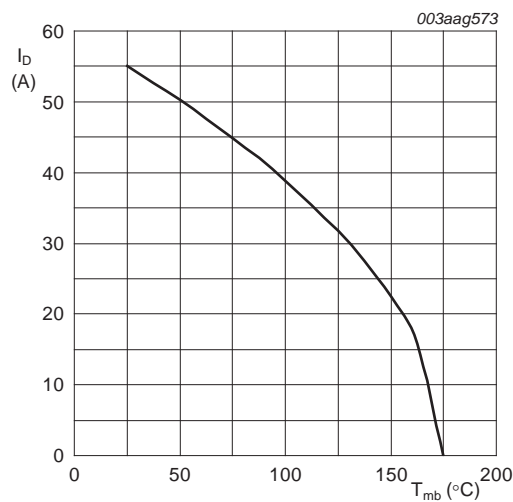


Fig 1. Continuous drain current as a function of mounting base temperature

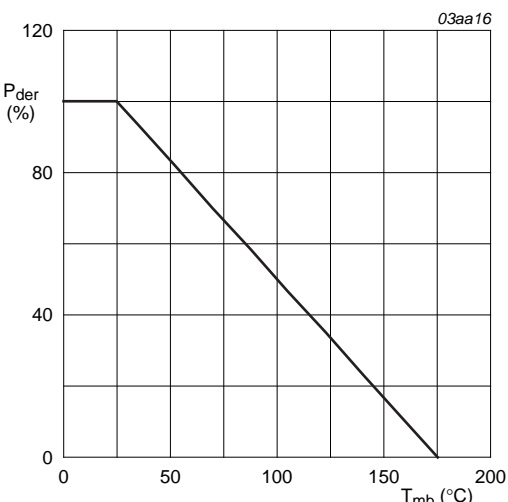
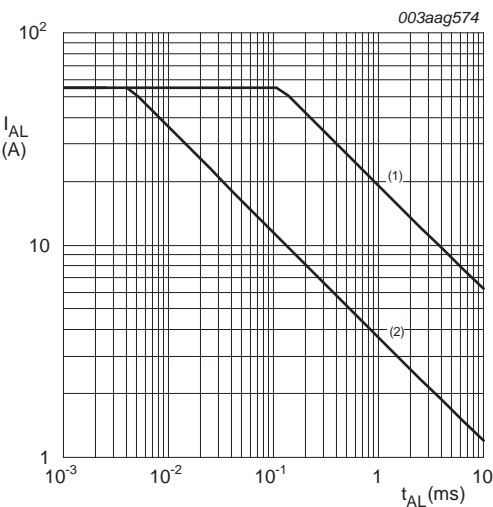
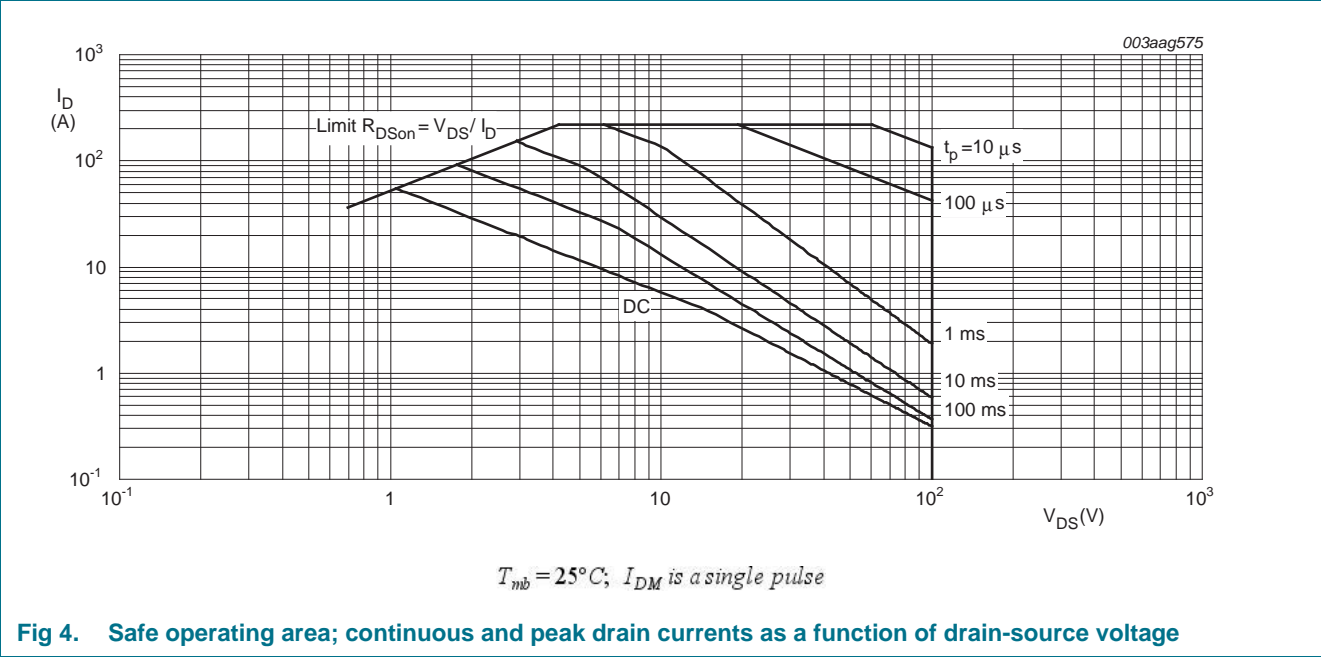


Fig 2. Normalized total power dissipation as a function of mounting base temperature



(1)  $T_{j (init)} = 25^\circ C$ ; (2)  $T_{j (init)} = 130^\circ C$

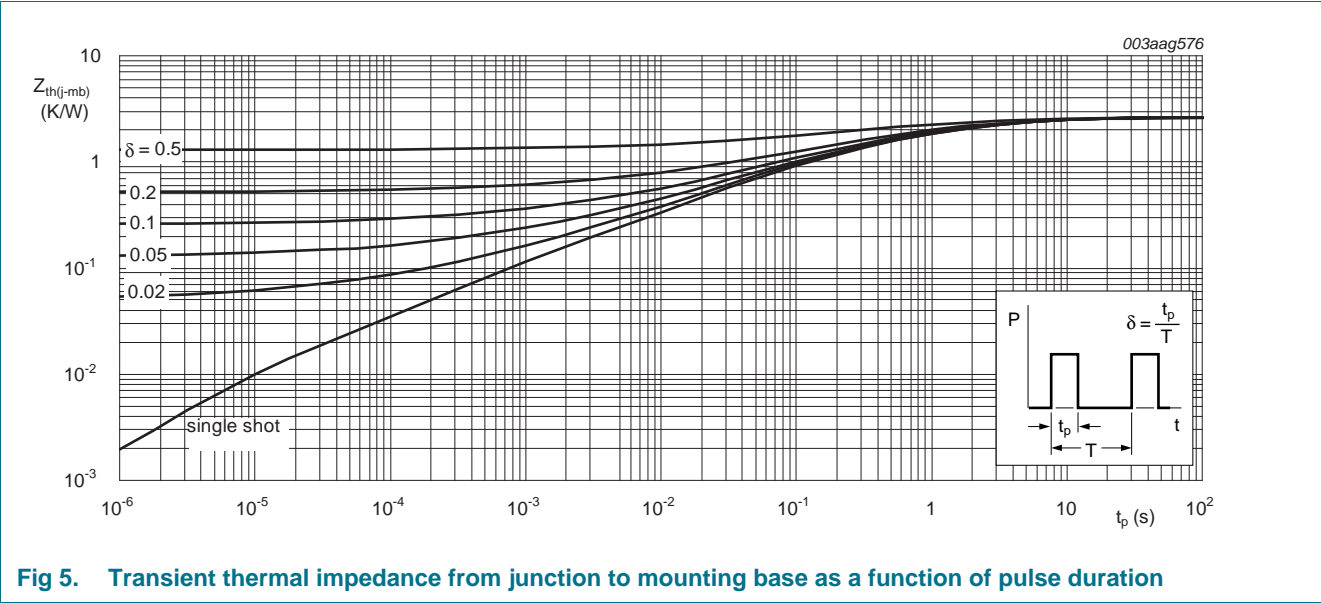
Fig 3. Single pulse avalanche rating; avalanche current as a function of avalanche time



5. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see <a href="#">Figure 5</a>	-	2.35	2.6	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	vertical in free air	-	55	-	K/W



6. Isolation characteristics

Table 6. Isolation characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$C_{isol}$	isolation capacitance		<a href="#">[1]</a> -	10	-	pF
$V_{isol(RMS)}$	RMS isolation voltage	50 Hz ≤ f ≤ 60 Hz; RH ≤ 65 %; sinusoidal waveform; clean and dust free	-	-	2500	V

[1] f = 1 MHz

## 7. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250\ \mu\text{A}$ ; $V_{GS} = 0\ \text{V}$ ; $T_j = 25\ ^\circ\text{C}$	100	-	-	V
		$I_D = 250\ \mu\text{A}$ ; $V_{GS} = 0\ \text{V}$ ; $T_j = -55\ ^\circ\text{C}$	90	-	-	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1\ \text{mA}$ ; $V_{DS} = V_{GS}$ ; $T_j = 25\ ^\circ\text{C}$ ; see <a href="#">Figure 10</a> ; see <a href="#">Figure 11</a>	2	3	4	V
		$I_D = 1\ \text{mA}$ ; $V_{DS} = V_{GS}$ ; $T_j = 175\ ^\circ\text{C}$ ; see <a href="#">Figure 10</a>	1	-	-	V
		$I_D = 1\ \text{mA}$ ; $V_{DS} = V_{GS}$ ; $T_j = -55\ ^\circ\text{C}$ ; see <a href="#">Figure 10</a>	-	-	4.6	V
$I_{DSS}$	drain leakage current	$V_{DS} = 100\ \text{V}$ ; $V_{GS} = 0\ \text{V}$ ; $T_j = 25\ ^\circ\text{C}$	-	-	5	$\mu\text{A}$
		$V_{DS} = 100\ \text{V}$ ; $V_{GS} = 0\ \text{V}$ ; $T_j = 100\ ^\circ\text{C}$	-	-	100	$\mu\text{A}$
$I_{GSS}$	gate leakage current	$V_{GS} = 20\ \text{V}$ ; $V_{DS} = 0\ \text{V}$ ; $T_j = 25\ ^\circ\text{C}$	-	2	100	nA
		$V_{GS} = -20\ \text{V}$ ; $V_{DS} = 0\ \text{V}$ ; $T_j = 25\ ^\circ\text{C}$	-	2	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\ \text{V}$ ; $I_D = 15\ \text{A}$ ; $T_j = 25\ ^\circ\text{C}$ ; see <a href="#">Figure 12</a> ; see <a href="#">Figure 13</a>	-	5.4	6.8	mΩ
		$V_{GS} = 10\ \text{V}$ ; $I_D = 15\ \text{A}$ ; $T_j = 100\ ^\circ\text{C}$ ; see <a href="#">Figure 13</a>	-	9.45	11.9	mΩ
		$V_{GS} = 10\ \text{V}$ ; $I_D = 15\ \text{A}$ ; $T_j = 175\ ^\circ\text{C}$ ; see <a href="#">Figure 13</a>	-	15.1	19	mΩ
$R_G$	internal gate resistance (AC)	$f = 1\ \text{MHz}$	-	0.74	-	Ω
<b>Dynamic characteristics</b>						
$Q_{G(tot)}$	total gate charge	$I_D = 15\ \text{A}$ ; $V_{DS} = 50\ \text{V}$ ; $V_{GS} = 10\ \text{V}$ ; see <a href="#">Figure 14</a> ; see <a href="#">Figure 15</a>	-	121	-	nC
$Q_{GS}$	gate-source charge		-	26.3	-	nC
$Q_{GS(th)}$	pre-threshold gate-source charge		-	11	-	nC
$Q_{GS(th-pl)}$	post-threshold gate-source charge		-	15.3	-	nC
$Q_{GD}$	gate-drain charge		-	34	-	nC
$V_{GS(pl)}$	gate-source plateau voltage	$I_D = 15\ \text{A}$ ; $V_{DS} = 50\ \text{V}$ ; see <a href="#">Figure 14</a> ; see <a href="#">Figure 15</a>	-	4.1	-	V
$C_{iss}$	input capacitance	$V_{DS} = 50\ \text{V}$ ; $V_{GS} = 0\ \text{V}$ ; $f = 1\ \text{MHz}$ ; $T_j = 25\ ^\circ\text{C}$ ; see <a href="#">Figure 16</a> ; see <a href="#">Figure 17</a>	-	6686	-	pF
$C_{oss}$	output capacitance	$V_{DS} = 50\ \text{V}$ ; $V_{GS} = 0\ \text{V}$ ; $f = 1\ \text{MHz}$ ; $T_j = 25\ ^\circ\text{C}$ ; see <a href="#">Figure 16</a>	-	438	-	pF
$C_{rss}$	reverse transfer capacitance	$V_{DS} = 50\ \text{V}$ ; $V_{GS} = 0\ \text{V}$ ; $f = 1\ \text{MHz}$ ; $T_j = 25\ ^\circ\text{C}$ ; see <a href="#">Figure 16</a> ; see <a href="#">Figure 17</a>	-	272	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = 50\ \text{V}$ ; $R_L = 4\ \Omega$ ; $V_{GS} = 10\ \text{V}$ ; $R_{G(ext)} = 4.7\ \Omega$ ; $T_j = 25\ ^\circ\text{C}$	-	29	-	ns
$t_r$	rise time		-	30	-	ns
$t_{d(off)}$	turn-off delay time		-	94	-	ns
$t_f$	fall time		-	43	-	ns

Table 7. Characteristics ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Source-drain diode						
$V_{SD}$	source-drain voltage	$I_S = 10\text{ A}$ ; $V_{GS} = 0\text{ V}$ ; $T_J = 25\text{ °C}$ ; see Figure 18	-	0.76	1.2	V
$t_{rr}$	reverse recovery time	$I_S = 10\text{ A}$ ; $dI_S/dt = -100\text{ A/}\mu\text{s}$ ;	-	64	-	ns
$Q_r$	recovered charge	$V_{GS} = 0\text{ V}$ ; $V_{DS} = 50\text{ V}$	-	167	-	nC

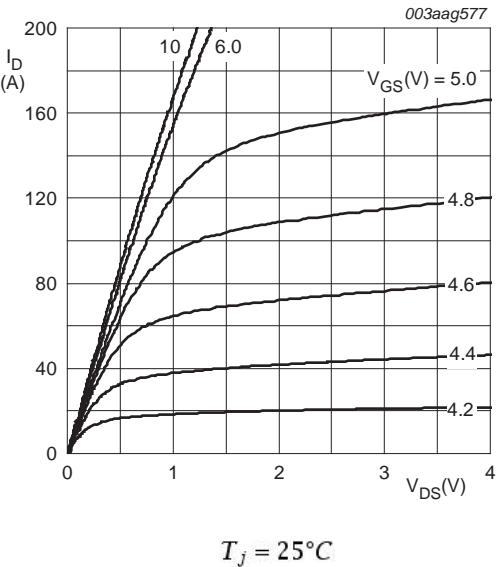


Fig 6. Output characteristics; drain current as a function of drain-source voltage; typical values

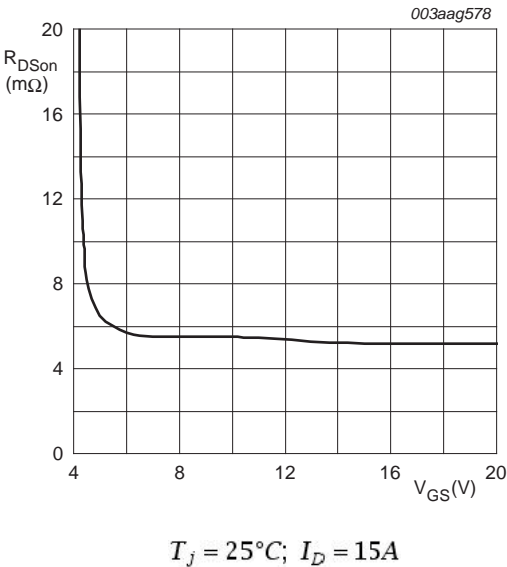


Fig 7. Drain-source on-state resistance as a function of gate-source voltage; typical values

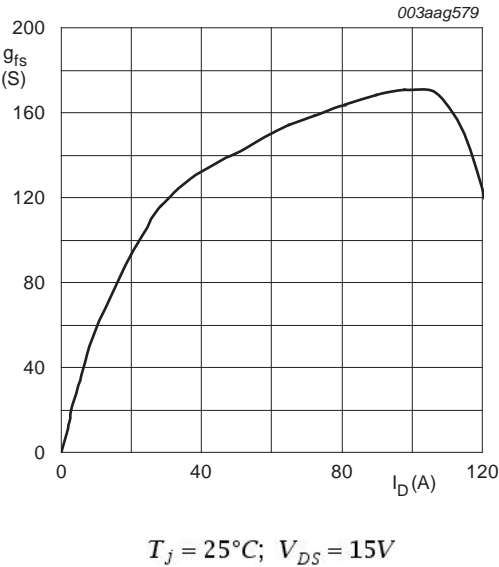


Fig 8. Forward transconductance as a function of drain current; typical values

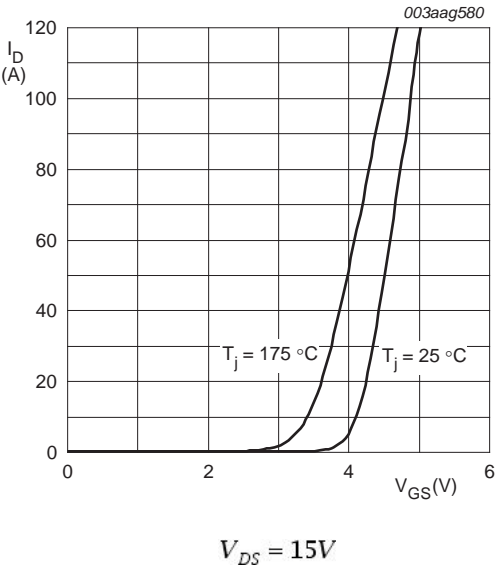
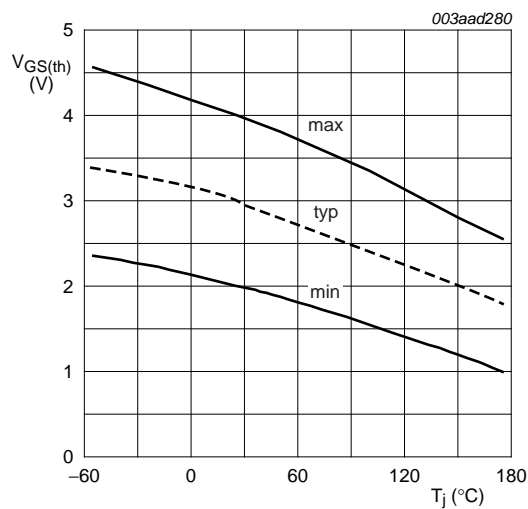
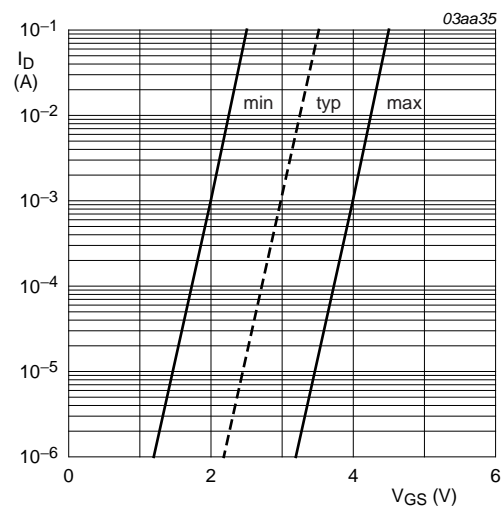


Fig 9. Transfer characteristics; drain current as a function of gate-source voltage; typical values



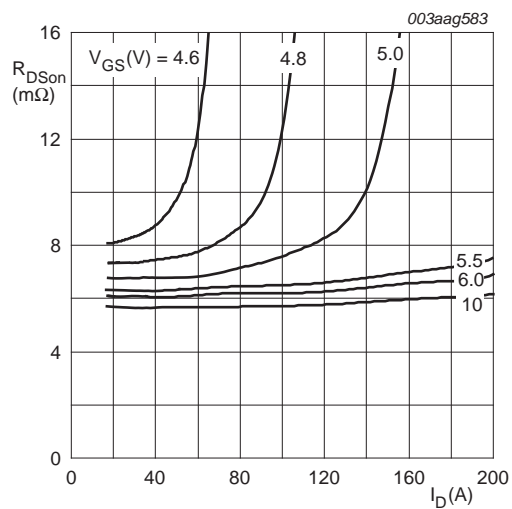
$I_D = 1 \text{ mA}; V_{DS} = V_{GS}$

Fig 10. Gate-source threshold voltage as a function of junction temperature



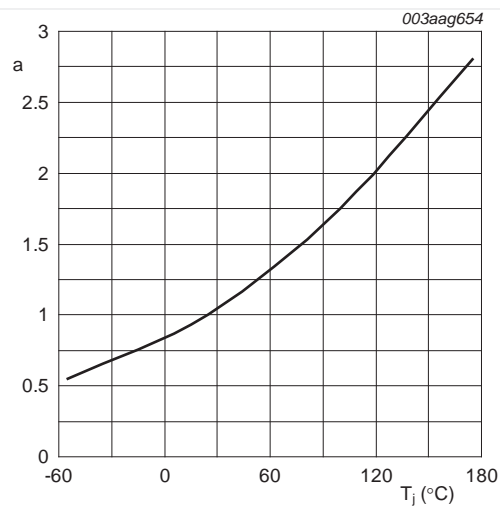
$T_j = 25 \text{ }^{\circ}\text{C}; V_{DS} = 5 \text{ V}$

Fig 11. Sub-threshold drain current as a function of gate-source voltage



$T_j = 25 \text{ }^{\circ}\text{C}$

Fig 12. Drain-source on-state resistance as a function of drain current; typical values



$a = \frac{R_{DS(on)}}{R_{DS(on)}(25^{\circ}\text{C})}$

Fig 13. Normalized drain-source on-state resistance factor as a function of junction temperature



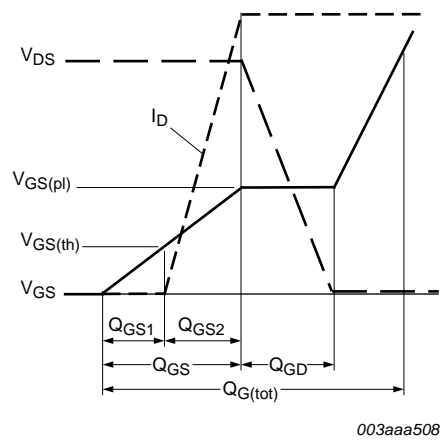
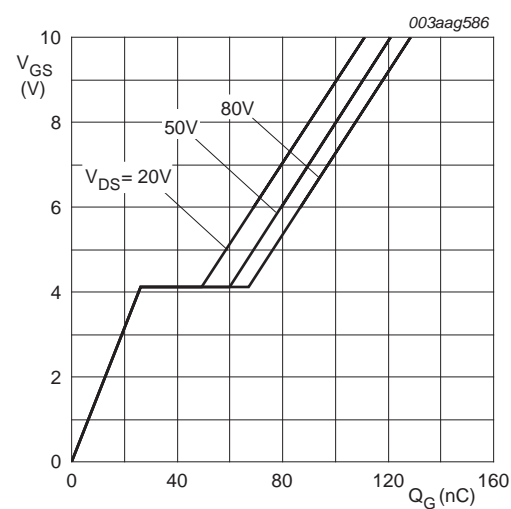
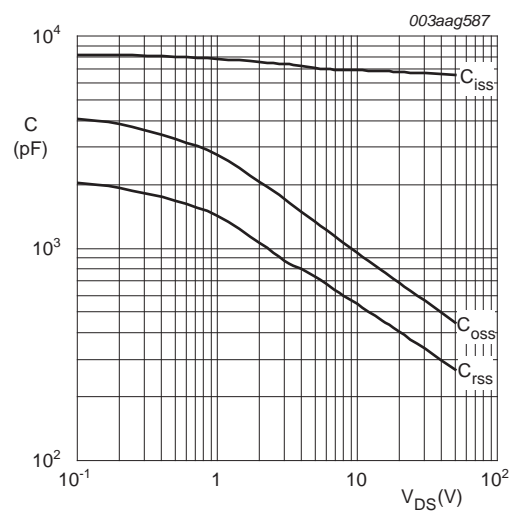


Fig 14. Gate charge waveform definitions



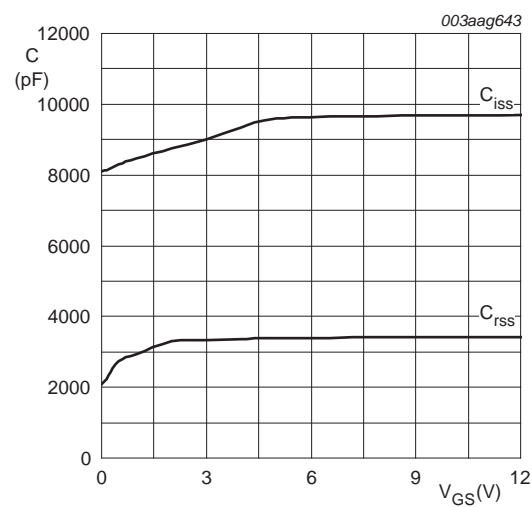
$T_j = 25^{\circ}C$ ;  $I_D = 15A$

Fig 15. Gate-source voltage as a function of gate charge; typical values



$V_{GS} = 0V$ ;  $f = 1MHz$

Fig 16. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



$f = 1MHz$ ,  $V_{DS} = 0V$

Fig 17. Input and reverse transfer capacitances as a function of gate-source voltage, typical values

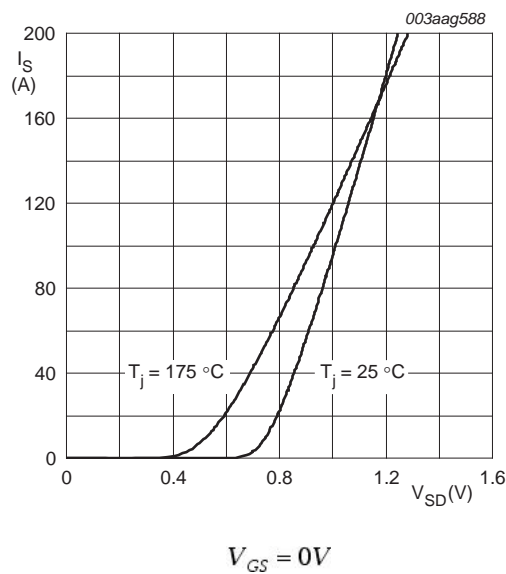


Fig 18. Source current as a function of source-drain voltage; typical values

8. Package outline

Plastic single-ended package; isolated heatsink mounted;  
1 mounting hole; 3-lead TO-220 'full pack'

SOT186A

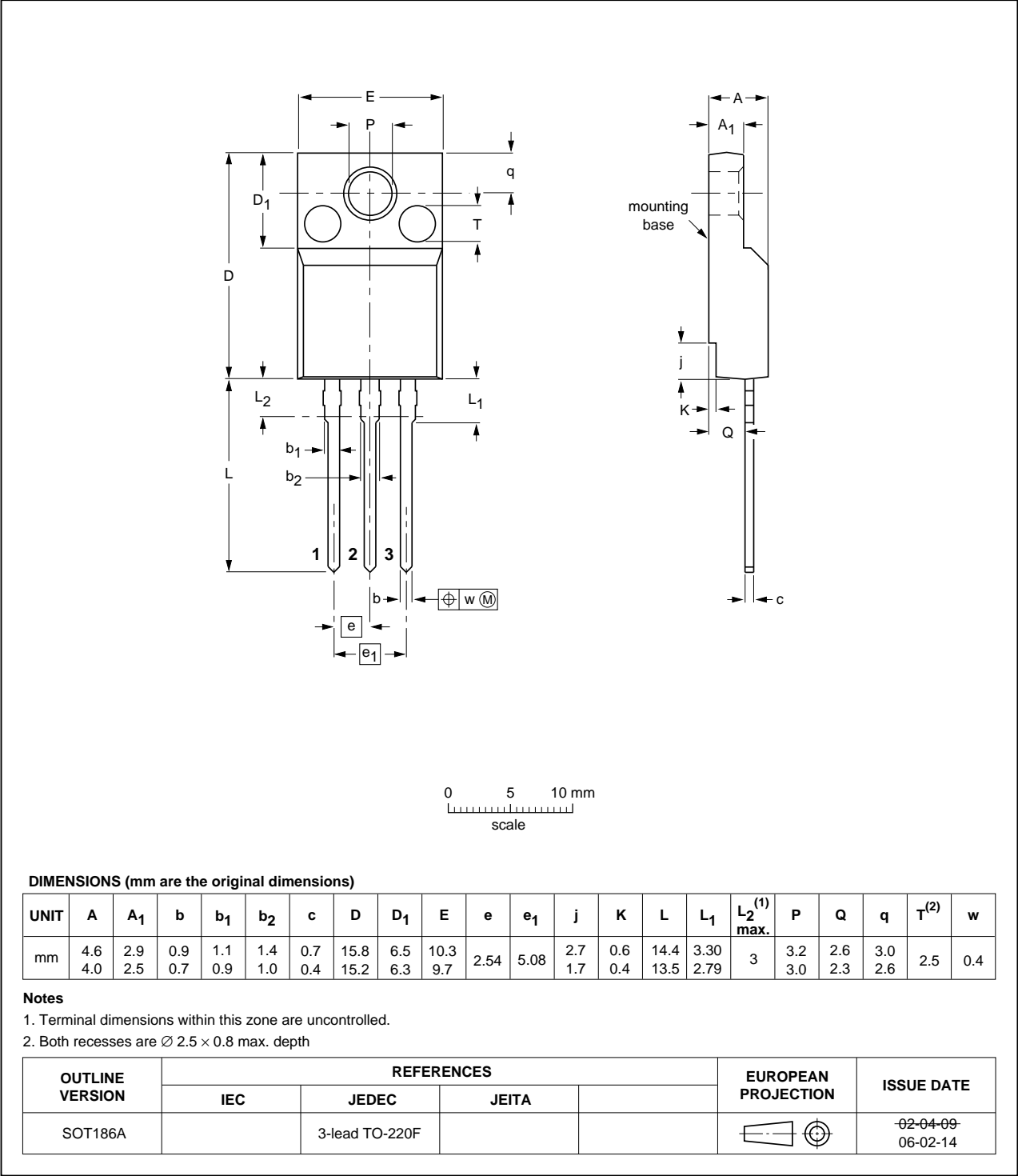


Fig 19. Package outline SOT186A (TO-220F)

## 9. Revision history

**Table 8.** Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PSMN7R0-100XS v.3	20120306	Product data sheet	-	PSMN7R0-100XS v.2
Modifications:	<ul style="list-style-type: none"><li>• Status changed from preliminary to product.</li><li>• Various changes to content.</li></ul>			
PSMN7R0-100XS v.2	20111021	Preliminary data sheet	-	PSMN7R0-100XS v.1

## 10. Legal information

### 10.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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## 12. Contents

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<b>1</b>	<b>Product profile</b> . . . . .	<b>1</b>
1.1	General description . . . . .	1
1.2	Features and benefits . . . . .	1
1.3	Applications . . . . .	1
1.4	Quick reference data . . . . .	1
<b>2</b>	<b>Pinning information</b> . . . . .	<b>2</b>
<b>3</b>	<b>Ordering information</b> . . . . .	<b>2</b>
<b>4</b>	<b>Limiting values</b> . . . . .	<b>2</b>
<b>5</b>	<b>Thermal characteristics</b> . . . . .	<b>5</b>
<b>6</b>	<b>Isolation characteristics</b> . . . . .	<b>5</b>
<b>7</b>	<b>Characteristics</b> . . . . .	<b>6</b>
<b>8</b>	<b>Package outline</b> . . . . .	<b>11</b>
<b>9</b>	<b>Revision history</b> . . . . .	<b>12</b>
<b>10</b>	<b>Legal information</b> . . . . .	<b>13</b>
10.1	Data sheet status . . . . .	13
10.2	Definitions . . . . .	13
10.3	Disclaimers . . . . .	13
10.4	Trademarks . . . . .	14
<b>11</b>	<b>Contact information</b> . . . . .	<b>14</b>

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